EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	10720	((align$8) near4 (resist or photoresist or pr or photo adj (defin$4 or cur$4) or photodefin$4 or photocur$4))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/04 17:18
L2	24679	(multichip multi-chip multi adj chip) adj module mcm	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/04 17:19
L3	101789	(second! top upper third topside) near2 (ic die chip dice)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/04 17:19
L4	23	1 same (2 3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/04 17:20
L5	458	1 and (2 3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/04 17:45
L6	349	5 and (@ad < "20030602")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/04 17:44
L7	2	"20050170609".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/04 17:45
L8	10	(1 and (2 3)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/04 17:45
L9	4813	((438/622) or (438/626) or (438/633) or (438/691)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/04 17:47

L10	6930	((257/750) or (257/774) or (257/723) or (257/e23.174) or (257/e23.175)). CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/04 17:50
S1	659351	wiring or interconnect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/05/19 18:08
S23 7	446	S236 and S231 and S228 and (@ad < "20030606")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/03 19:07
S24 1	97782	(second! top upper third topside) near2 (ic die chip dice)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/04 17:19
S25 0	24676	(multichip multi-chip multi adj chip) adj module mcm	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/04 17:19
S25 1	654043	via adj hole via-hole viahole plug	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/03 19:07
S25 2	5066282	(resin$4 epoxy photodefin$4 light uv ultraviolet)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/03 19:07
S25 3	201025	novolak polynororene polyimide polyybenzoxazole	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/03 19:07
S25 4	103540	S253 with S252	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/03 19:07

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S25 5	453	S254 and S251 and S250 and (@ad < "20030606")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/03 19:07
S25 6	271	(((second! or another or upper or above) near (wafer or substrate or chip or ic or die or dice) same (adhesiv$4 or glue or elastomer$4) same (curable or curing or cure or set or setting or harden$4) same (etch$4 or remov$4)) not optic$4.ti.) and (@ad < "20030602")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/04 17:20
S25 7	34	((((second! or another or upper or above) near (wafer or substrate or chip or ic or die or dice) same (adhesiv$4 or glue or elastomer$4) same (curable or curing or cure or set or setting or harden$4) same (etch$4 or remov$4)) not optic$4.ti.)).clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/03 20:05